

Cascadable Silicon Bipolar MMIC Amplifier

Technical Data

MSA-0386

Features

- **Cascadable 50 Ω Gain Block**
- **3 dB Bandwidth:**
DC to 2.4 GHz
- **12.0 dB Typical Gain at 1.0 GHz**
- **10.0 dBm Typical P_{1 dB} at 1.0 GHz**
- **Unconditionally Stable (k>1)**
- **Surface Mount Plastic Package**
- **Tape-and-Reel Packaging Option Available^[1]**

Note:

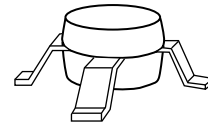
1. Refer to PACKAGING section "Tape-and-Reel Packaging for Surface Mount Semiconductors".

Description

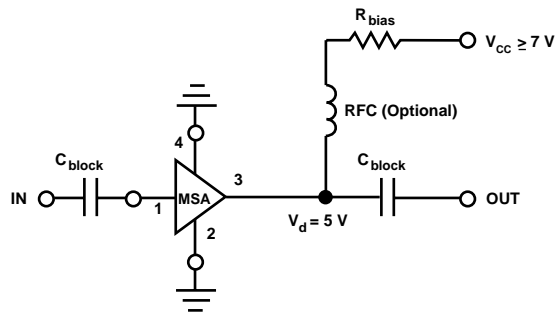
The MSA-0386 is a high performance silicon bipolar Monolithic Microwave Integrated Circuit (MMIC) housed in a low cost, surface mount plastic package. This MMIC is designed for use as a general purpose 50 Ω gain block. Typical applications include narrow and broad band IF and RF amplifiers in commercial and industrial applications.

The MSA-series is fabricated using HP's 10 GHz f_T , 25 GHz f_{MAX} , silicon bipolar MMIC process which uses nitride self-alignment, ion implantation, and gold metallization to achieve excellent performance, uniformity and reliability. The use of an external bias resistor for temperature and current stability also allows bias flexibility.

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Typical Biasing Configuration



MSA-0386 Absolute Maximum Ratings

| Parameter | Absolute Maximum ^[1] |
|------------------------------------|---------------------------------|
| Device Current | 70 mA |
| Power Dissipation ^[2,3] | 400 mW |
| RF Input Power | +13 dBm |
| Junction Temperature | 150°C |
| Storage Temperature | -65 to 150°C |

Thermal Resistance^[2,4]:

$$\theta_{jc} = 115^{\circ}\text{C/W}$$

Notes:

1. Permanent damage may occur if any of these limits are exceeded.
2. $T_{\text{CASE}} = 25^{\circ}\text{C}$.
3. Derate at 9.5 mW/°C for $T_{\text{C}} > 116^{\circ}\text{C}$.
4. See MEASUREMENTS section "Thermal Resistance" for more information.

Electrical Specifications^[1], $T_{\text{A}} = 25^{\circ}\text{C}$

| Symbol | Parameters and Test Conditions: $I_{\text{d}} = 35 \text{ mA}$, $Z_{\text{o}} = 50 \Omega$ | Units | Min. | Typ. | Max. |
|-----------------------|---|-------|------|--------------|------|
| G_{P} | Power Gain ($ S_{21} ^2$) f = 0.1 GHz f = 1.0 GHz | dB | 10.0 | 12.5 12.0 | |
| ΔG_{P} | Gain Flatness f = 0.1 to 1.6 GHz | dB | | ± 0.7 | |
| $f_{3 \text{ dB}}$ | 3 dB Bandwidth | GHz | | 2.4 | |
| VSWR | Input VSWR f = 0.1 to 3.0 GHz | | | 1.5:1 | |
| | Output VSWR f = 0.1 to 3.0 GHz | | | 1.7:1 | |
| NF | 50 Ω Noise Figure f = 1.0 GHz | dB | | 6.0 | |
| $P_{1 \text{ dB}}$ | Output Power at 1 dB Gain Compression f = 1.0 GHz | dBm | | 10.0 | |
| IP_3 | Third Order Intercept Point f = 1.0 GHz | dBm | | 23.0 | |
| t_{D} | Group Delay f = 1.0 GHz | psec | | 140 | |
| V_{d} | Device Voltage | V | 4.0 | 5.0 | 6.0 |
| dV/dT | Device Voltage Temperature Coefficient | mV/°C | | -8.0 | |

Note:

1. The recommended operating current range for this device is 20 to 40 mA. Typical performance as a function of current is on the following page.

Part Number Ordering Information

| Part Number | No. of Devices | Container |
|--------------|----------------|----------------|
| MSA-0386-TR1 | 1000 | 7" Reel |
| MSA-0386-BLK | 100 | Antistatic Bag |

For more information, see "Tape and Reel Packaging for Semiconductor Devices".

MSA-0386 Typical Scattering Parameters ($Z_0 = 50 \Omega$, $T_A = 25^\circ\text{C}$, $I_d = 35 \text{ mA}$)

| Freq. GHz | S_{11} | | S_{21} | | | S_{12} | | | S_{22} | |
|--------------|----------|-----|----------|------|-----|----------|------|-----|----------|------|
| | Mag | Ang | dB | Mag | Ang | dB | Mag | Ang | Mag | Ang |
| 0.1 | .11 | 174 | 12.5 | 4.22 | 175 | -18.3 | .122 | 1 | .13 | -11 |
| 0.2 | .11 | 169 | 12.5 | 4.20 | 170 | -18.2 | .124 | 2 | .13 | -20 |
| 0.4 | .11 | 159 | 12.4 | 4.16 | 159 | -18.1 | .124 | 5 | .14 | -41 |
| 0.6 | .10 | 149 | 12.2 | 4.09 | 149 | -17.9 | .128 | 8 | .15 | -60 |
| 0.8 | .10 | 142 | 12.1 | 4.00 | 139 | -17.6 | .131 | 9 | .16 | -78 |
| 1.0 | .09 | 137 | 11.9 | 3.93 | 129 | -17.4 | .136 | 11 | .18 | -93 |
| 1.5 | .09 | 139 | 11.2 | 3.61 | 106 | -16.6 | .149 | 14 | .20 | -129 |
| 2.0 | .12 | 149 | 10.3 | 3.28 | 83 | -15.3 | .171 | 13 | .23 | -157 |
| 2.5 | .18 | 150 | 9.4 | 2.95 | 66 | -14.4 | .190 | 12 | .26 | -176 |
| 3.0 | .25 | 142 | 8.3 | 2.60 | 48 | -13.7 | .207 | 9 | .29 | 167 |
| 3.5 | .32 | 133 | 7.2 | 2.29 | 31 | -13.2 | .219 | 3 | .30 | 152 |
| 4.0 | .40 | 124 | 6.0 | 2.01 | 15 | -13.0 | .224 | -1 | .31 | 142 |
| 5.0 | .53 | 106 | 3.7 | 1.53 | -13 | -12.8 | .228 | -11 | .32 | 128 |

A model for this device is available in the DEVICE MODELS section.

Typical Performance, $T_A = 25^\circ\text{C}$

(unless otherwise noted)

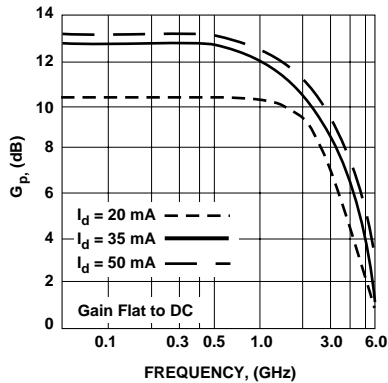


Figure 1. Typical Power Gain vs. Frequency, $T_A = 25^\circ\text{C}$.

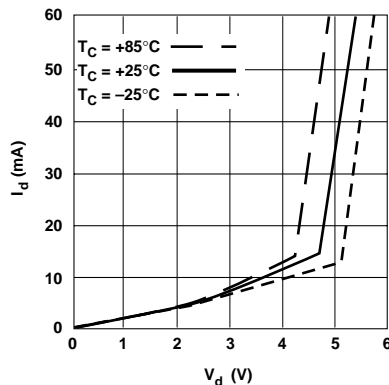


Figure 2. Device Current vs. Voltage.

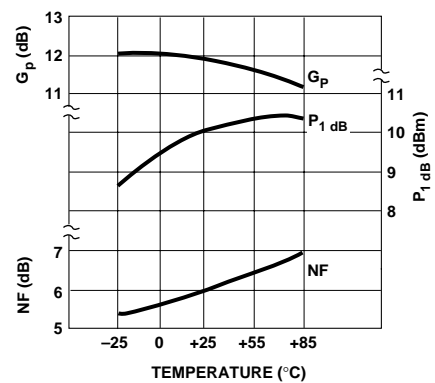


Figure 3. Output Power at 1 dB Gain Compression, NF and Power Gain vs. Case Temperature, $f = 1.0 \text{ GHz}$, $I_d = 35 \text{ mA}$.

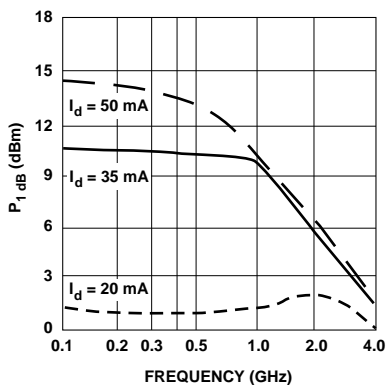


Figure 4. Output Power at 1 dB Gain Compression vs. Frequency.

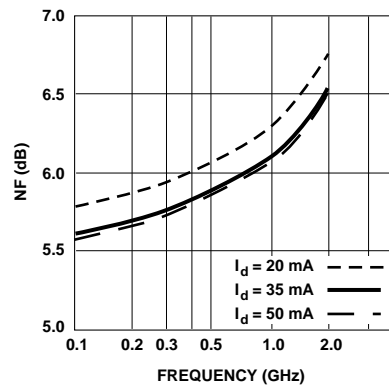


Figure 5. Noise Figure vs. Frequency.

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